

EL ALFS series

ALFS1G-C010001H-AM



Features

- Package : SMD ceramic package
- Typ. Luminous Flux : 400 lm @1000mA
- Viewing angle : 120°
- ESD : up to 8KV
- MSL : 2
- Qualifications : According to AEC-Q102
- Sulfur robustness : Class A1
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Applications

- Automotive Exterior Lighting
- Headlamp
- Daytime running light (DRL)
- Fog lamp

Contents

1. Characteristics	3
2. Absolute Maximum Ratings	4
3. Characteristics Graph.....	5
4. Binning Information	10
5. Part Number	16
6. Ordering Information	17
7. Mechanical Dimension	18
8. Recommended Soldering Pad	19
9. Reflow Soldering Profile.....	20
10. Packaging Information.....	21
11. Precaution for Use	23
12. Sulfur Test Criteria	24

1. Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward current ^[4]	I_F	50	1000	1500	mA	
Luminous Flux ^{[1][2]}	Φ_v	360	400	500	lm	$I_F=1000\text{mA}$
Forward Voltage ^[3]	V_F	2.90	3.30	3.80	V	$I_F=1000\text{mA}$
Viewing Angle	ϕ	---	120	---	deg	$I_F=1000\text{mA}$
Color	K	5180	---	6893	K	$I_F=1000\text{mA}$
Thermal Resistance (Junction to Solder)	$R_{th\ JS\ real}$	---	4.0	4.4	K/W	$I_F=1000\text{mA}$
	$R_{th\ JS\ el}$	---	3.0	3.4		

Notes:

1. Luminous flux measurement tolerance: $\pm 8\%$
2. The data of luminous flux measured at thermal pad= 25°C
3. Forward voltage measurement tolerance: $\pm 0.05\text{V}$
4. Current pulse time: 25ms

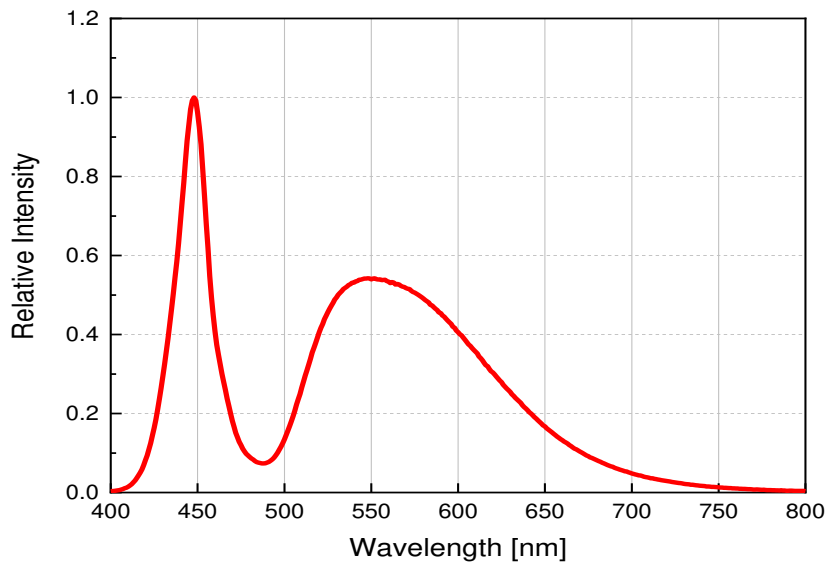
2. Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Reverse Voltage	V_R	Not designed for reverse operation	V
Power Dissipation	P_d	5700	mW
Forward Current	I_F	1500	mA
Junction Temperature	T_J	150	°C
Operating Temperature	T_{opr}	-40 ~ +125	°C
Storage Temperature	T_{stg}	-40 ~ +125	°C
ESD Sensitivity (R=1.5kΩ, C= 100pF)	ESD_{HBM}	8	KV
Soldering Temperature	Reflow	260	°C

3. Characteristics Graph

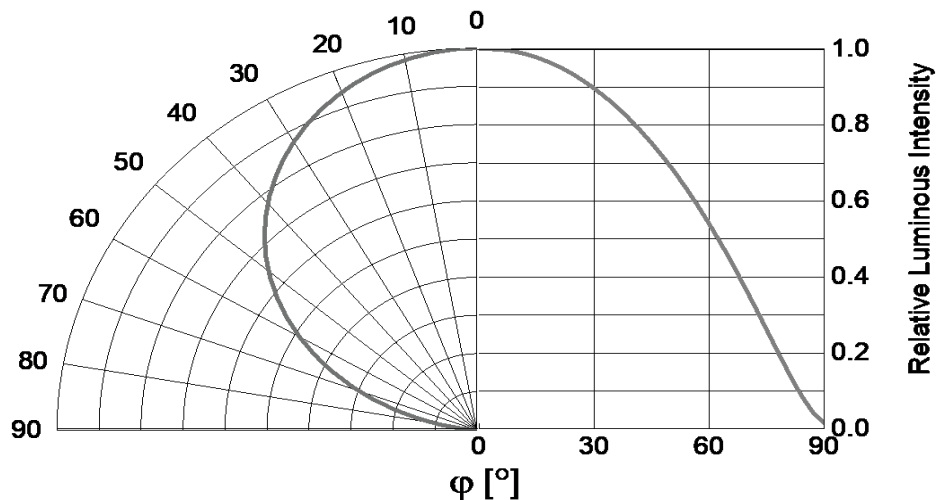
Wavelength Characteristics Relative Spectral Distribution @ $T_S = 25^\circ\text{C}$ 、 $I_F = 1000\text{mA}$

$$\Phi_V / \Phi_V (\text{Max.}) = f(\lambda)$$



Typical Diagram Characteristics of Radiation

$$\Phi_V / \Phi_V (0^\circ) = f(\varphi)$$

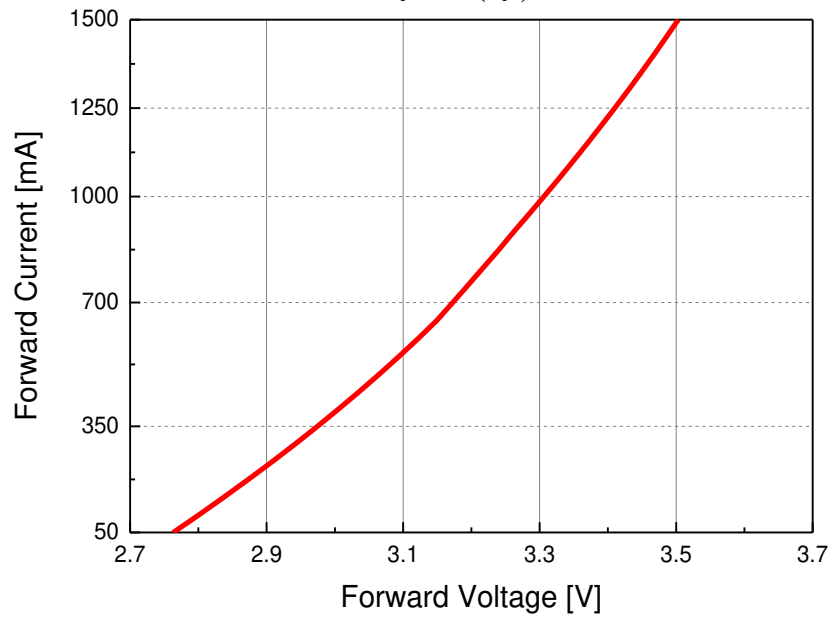


Notes:

1. φ is the off axis angle from lamp centerline where the luminous intensity is 1/2 of the peak value.
2. View angle tolerance is $\pm 5^\circ$

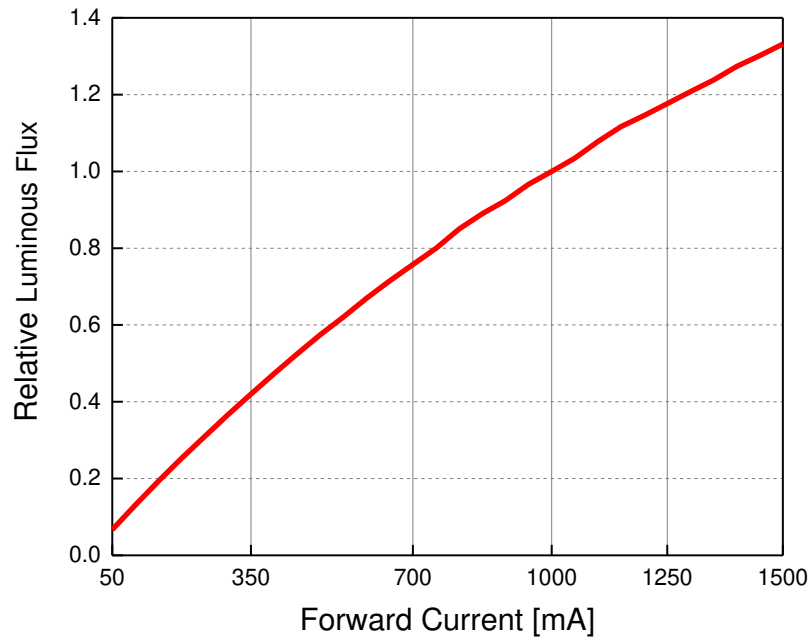
Forward Current vs. Forward Voltage @ T_s = 25°C

$$I_F = f(V_F)$$

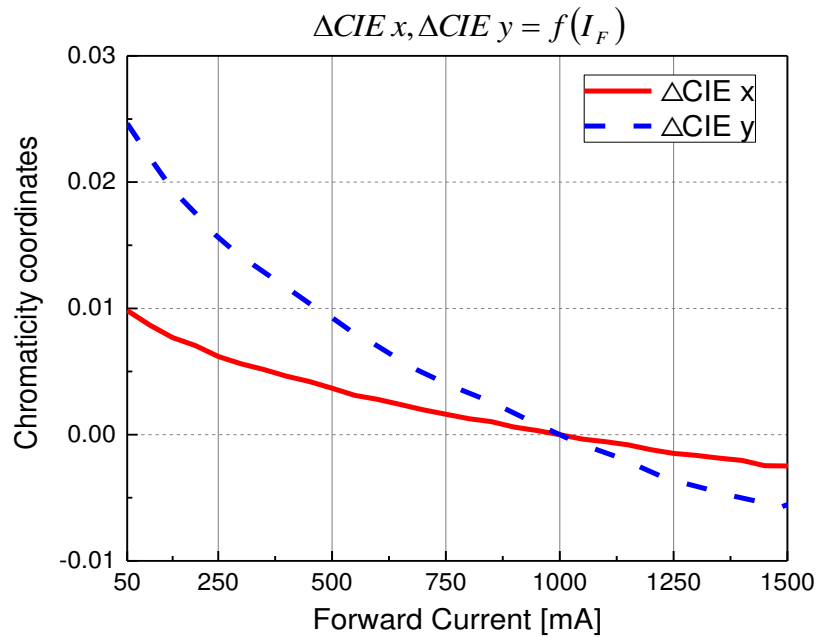


Relative Luminous Flux vs. Forward Current @ T_s = 25°C

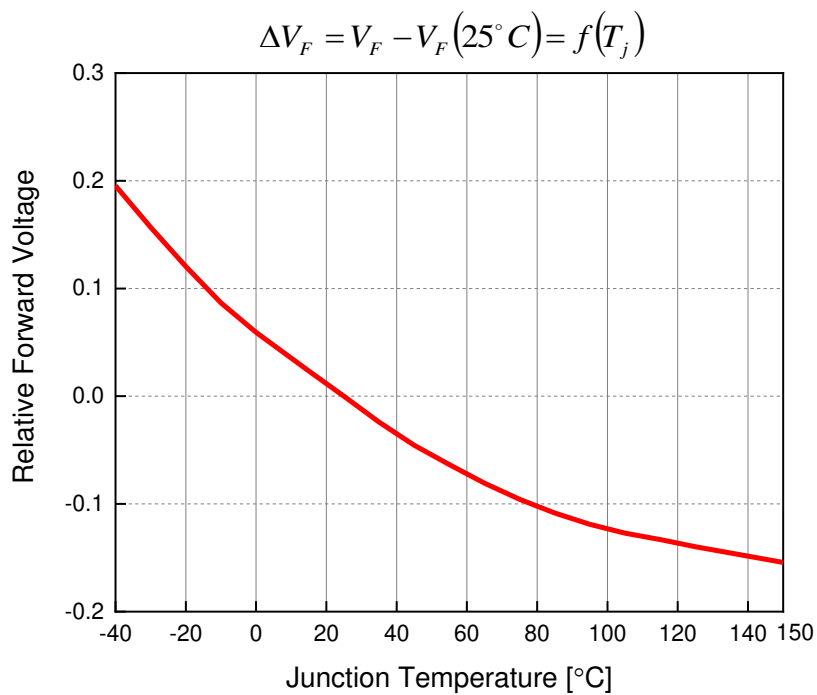
$$\Phi_V / \Phi_V(1000mA) = f(I_F)$$



Chromaticity Coordinates vs. Forward Current @ $T_s = 25^\circ\text{C}$



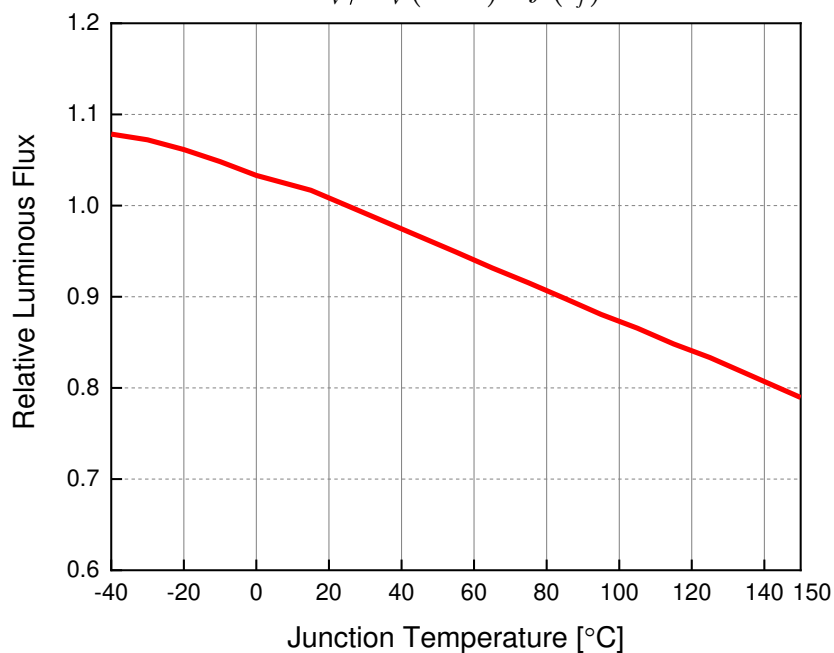
Relative Forward Voltage vs. Junction Temperature @ $I_F = 1000\text{mA}$



Relative Luminous Flux vs. Junction Temperature

@ $I_F = 1000\text{mA}$

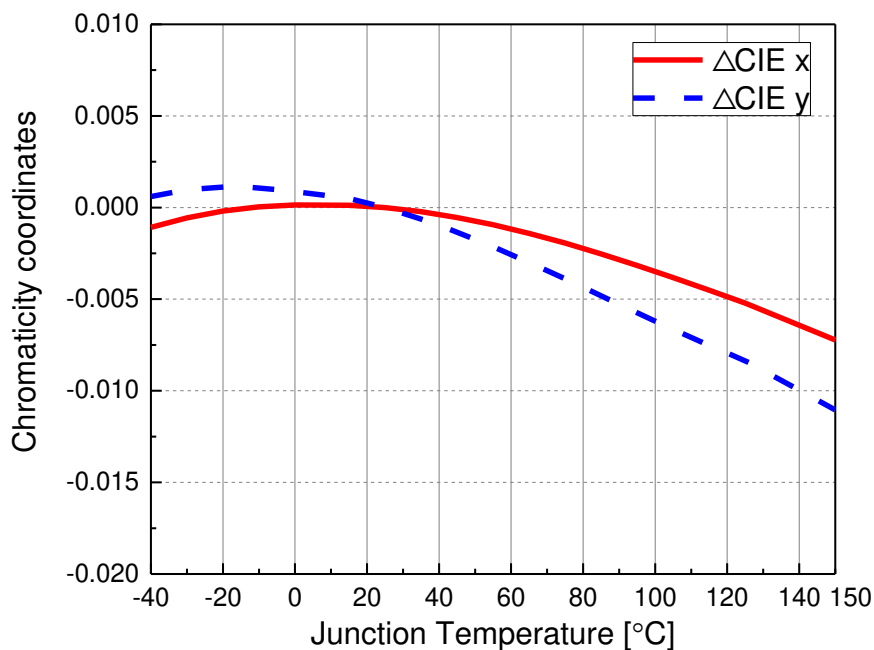
$$\Phi_V / \Phi_V(25^\circ\text{C}) = f(T_j)$$



Chromaticity Coordinates Shift vs. Junction Temperature

@ $I_F = 1000\text{mA}$

$$\Delta CIE\ x, \Delta CIE\ y = f(T_j)$$





4. Binning Information

Luminous Intensity Bins

[Cool White]			
Group	Bin	Minimum Photometric Flux (lm)	Maximum Photometric Flux (lm)
C	4	360	380
	5	380	400
	6	400	425
	7	425	450
	8	450	475
	9	475	500

Notes:

1. Luminous flux measurement tolerance: ±8%
2. Test current: Typical forward current
3. Current pulse time: 25ms

Forward Voltage Bins

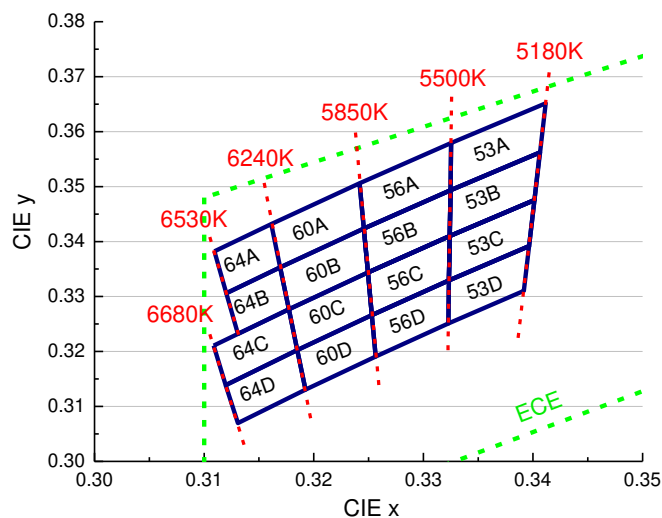
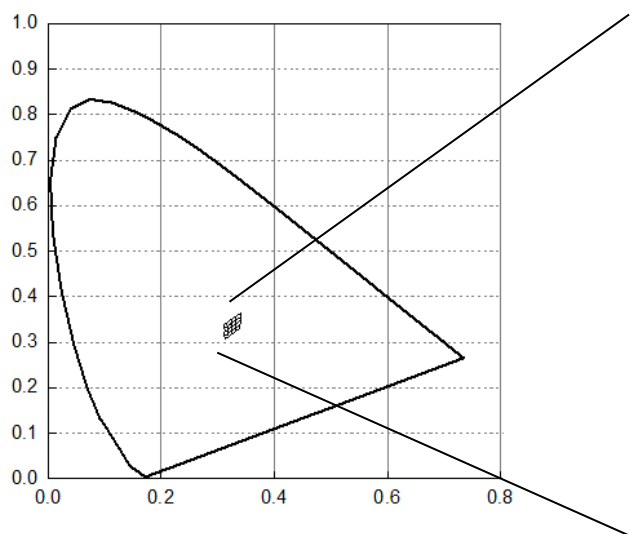
Group	Minimum Forward Voltage(V)	Maximum Forward Voltage(V)
1A	2.90	3.20
1B	3.20	3.50
1C	3.50	3.80

Notes:

1. Forward Voltage measurement tolerance: ±0.05V
2. Test current: Typical forward current
3. Current pulse time: 25ms

Color Bin Structure

ECE Bin Structure



Cool White Bin Coordinates

Bin	CIE x	CIE y
64A	0.3109	0.3382
	0.3161	0.3432
	0.3169	0.3353
	0.3120	0.3306
Reference Range: 6240~6530K		

Bin	CIE x	CIE y
64B	0.3120	0.3306
	0.3169	0.3353
	0.3177	0.3277
	0.3131	0.3232
Reference Range: 6240~6530K		

Bin	CIE x	CIE y
64C	0.3109	0.3211
	0.3177	0.3277
	0.3185	0.3203
	0.3120	0.3139
Reference Range: 6240~6680K		

Bin	CIE x	CIE y
64D	0.3120	0.3139
	0.3185	0.3203
	0.3192	0.3131
	0.3131	0.3070
Reference Range: 6240~6680K		

Bin	CIE x	CIE y
60A	0.3161	0.3432
	0.3242	0.3506
	0.3246	0.3424
	0.3169	0.3353
Reference Range: 5850~6240K		

Bin	CIE x	CIE y
60B	0.3169	0.3353
	0.3246	0.3424
	0.3249	0.3344
	0.3177	0.3277
Reference Range: 5850~6240K		

Bin	CIE x	CIE y
60C	0.3177	0.3277
	0.3249	0.3344
	0.3253	0.3266
	0.3185	0.3203
Reference Range: 5850~6240K		

Bin	CIE x	CIE y
60D	0.3185	0.3203
	0.3253	0.3266
	0.3256	0.3191
	0.3192	0.3131
Reference Range: 5850~6240K		

Bin	CIE x	CIE y
56A	0.3242	0.3506
	0.3325	0.3579
	0.3325	0.3493
	0.3246	0.3424
Reference Range: 5500~5850K		

Bin	CIE x	CIE y
56B	0.3246	0.3424
	0.3325	0.3493
	0.3324	0.3410
	0.3249	0.3344
Reference Range: 5500~5850K		

Bin	CIE x	CIE y
56C	0.3249	0.3344
	0.3324	0.3410
	0.3323	0.3329
	0.3253	0.3266
Reference Range: 5500~5850K		

Bin	CIE x	CIE y
56D	0.3253	0.3266
	0.3323	0.3329
	0.3323	0.3251
	0.3256	0.3191
Reference Range: 5500~5850K		

Bin	CIE x	CIE y
53A	0.3325	0.3579
	0.3412	0.3652
	0.3406	0.3562
	0.3325	0.3493
Reference Range: 5180~5500K		

Bin	CIE x	CIE y
53B	0.3325	0.3493
	0.3406	0.3562
	0.3401	0.3476
	0.3324	0.3410
Reference Range: 5180~5500K		

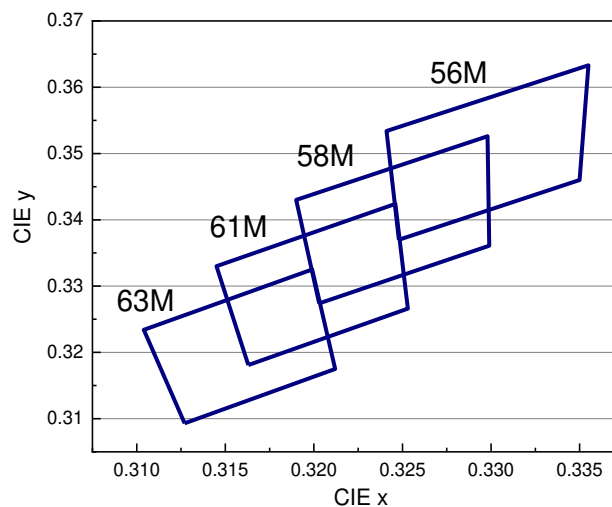
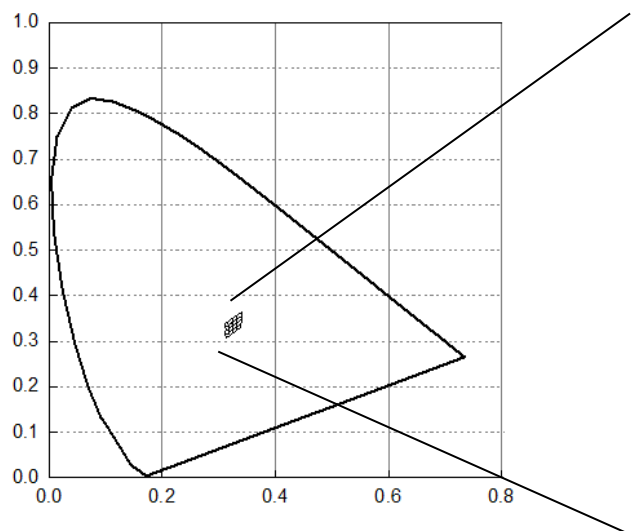
Bin	CIE x	CIE y
53C	0.3324	0.3410
	0.3401	0.3476
	0.3396	0.3392
	0.3323	0.3329
Reference Range: 5180~5500K		

Bin	CIE x	CIE y
53D	0.3323	0.3329
	0.3396	0.3392
	0.3392	0.3310
	0.3323	0.3251
Reference Range: 5180~5500K		

Notes:

1. Color coordinates measurement tolerance: ± 0.005
2. Test current: Typical forward current
3. Current pulse time: 25ms

Color Bin Structure



Cool White Bin Coordinates

Bin	CIE x	CIE y
63M	0.3127	0.3093
	0.3212	0.3175
	0.3199	0.3325
	0.3104	0.3234

Bin	CIE x	CIE y
61M	0.3163	0.3181
	0.3253	0.3266
	0.3246	0.3424
	0.3145	0.3330

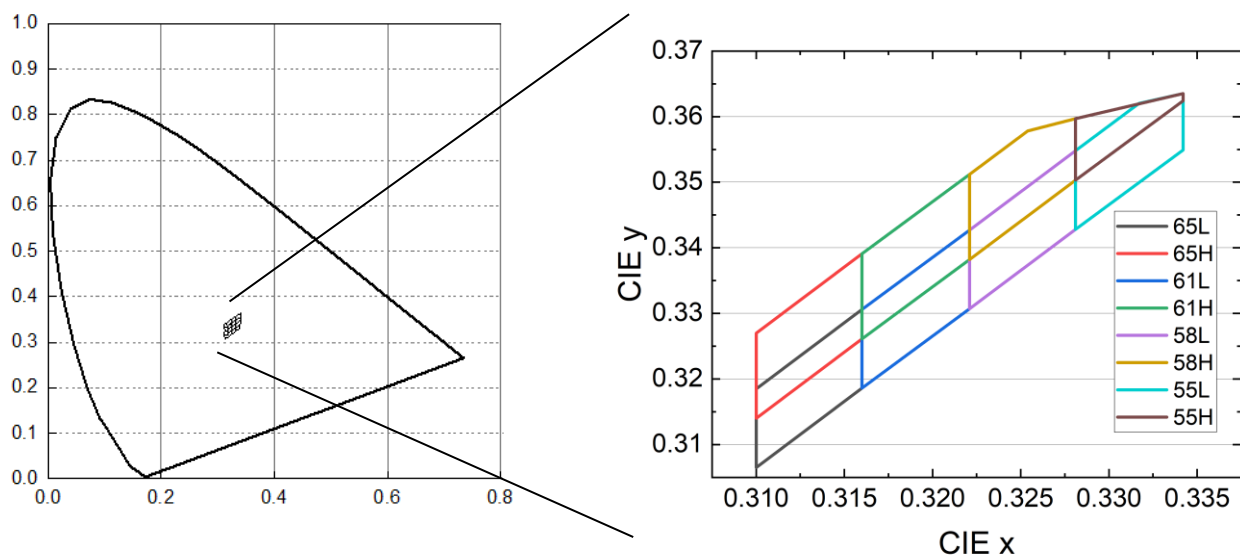
Bin	CIE x	CIE y
58M	0.3203	0.3274
	0.3299	0.3361
	0.3298	0.3526
	0.319	0.343

Bin	CIE x	CIE y
56M	0.3248	0.337
	0.335	0.346
	0.3355	0.3633
	0.3241	0.3534

Notes:

1. Color coordinates measurement tolerance: ± 0.005
2. Test current: Typical forward current
3. Current pulse time: 25ms

Color Bin Structure



Cool White Bin Coordinates

Bin	CIE x	CIE y
65L	0.3100	0.3065
	0.3100	0.3185
	0.3160	0.3306
	0.3160	0.3186

Bin	CIE x	CIE y
65H	0.3100	0.3140
	0.3100	0.3270
	0.3160	0.3391
	0.3160	0.3261

Bin	CIE x	CIE y
61L	0.3160	0.3186
	0.3160	0.3306
	0.3221	0.3427
	0.3221	0.3307

Bin	CIE x	CIE y
61H	0.3160	0.3261
	0.3160	0.3391
	0.3221	0.3512
	0.3221	0.3382

Bin	CIE x	CIE y
58L	0.3221	0.3307
	0.3221	0.3427
	0.3281	0.3548
	0.3281	0.3428

Bin	CIE x	CIE y
58H	0.3221	0.3382
	0.3221	0.3512
	0.3254	0.3578
	0.3281	0.3597
	0.3281	0.3503

Bin	CIE x	CIE y
55L	0.3281	0.3428
	0.3281	0.3548
	0.3317	0.3620
	0.3342	0.3635
	0.3342	0.3549

Bin	CIE x	CIE y
55H	0.3281	0.3503
	0.3281	0.3597
	0.3342	0.3635
	0.3342	0.3624

Notes:

1. Color coordinates measurement tolerance: ± 0.005
2. Test current: Typical forward current
3. Current pulse time: 25ms

5. Part Number

ALFS1G-C010001H-AM

Part number is designated with below details.

ALFS = product family name.

1 = chip number

G = Product type

C = Color ^[1]

0 = CRI (N/A=0 ; >70=7 ; >80=8 ; >90=9)

1000 = test current [mA]

1 = internal code

H = Brightness Level

AM = automotive application

Note :

^[1] Color :

Symbol	Description
C	Cool White
N	Neutral White
W	Warm White
PA	Phosphor Converted Amber
PR	Phosphor Converted Red
UB	Blue
IB	Ice Blue
SB	Sky Blue
UP	Purple
UG	Green
UY	Yellow
UYG	Brilliant Yellow Green
UPG	Pale Green
UA	Amber
UR	Red
SR	Super Red
RGB	RGB-Color

6. Ordering Information

ALFS1G-C010001H-**ABCDEFGHJKLMN-OP-AM**

Part Number of the ALFS	Order Code
ALFS1G-C010001H-AM	ALFS1G-C010001H- ABCDEFGHJKLMN-OP-AM

Order code contains information with below details :

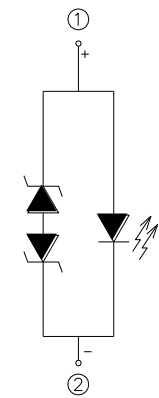
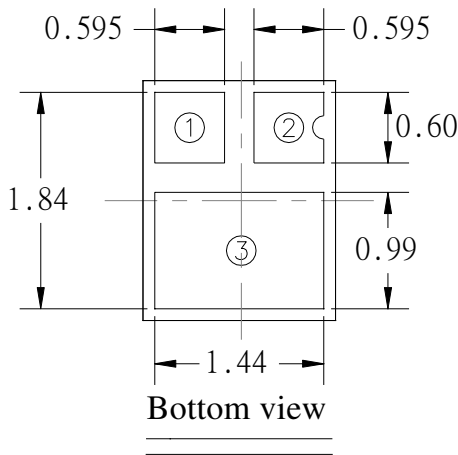
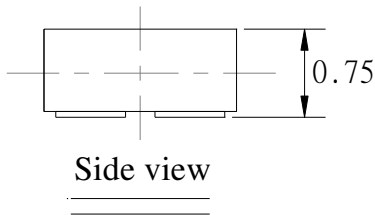
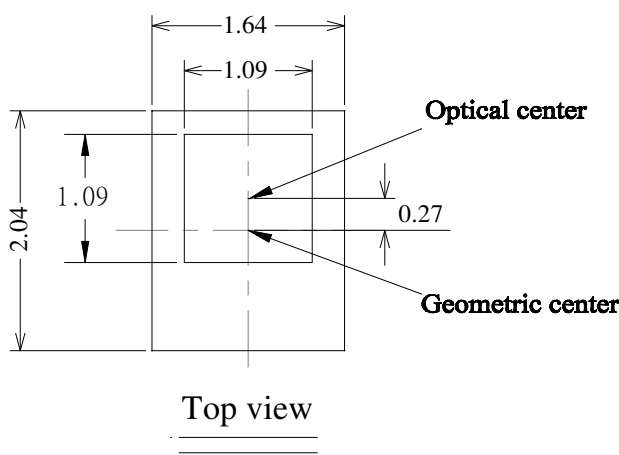
ABCDEF= min/max wavelength or CCT

GHIJ= min./max. luminous flux in [lm] or luminous intensity in [mcd]

KLMN = min./max. Forward Voltage

OP = Packing quantity (Minimum package)

7. Mechanical Dimension



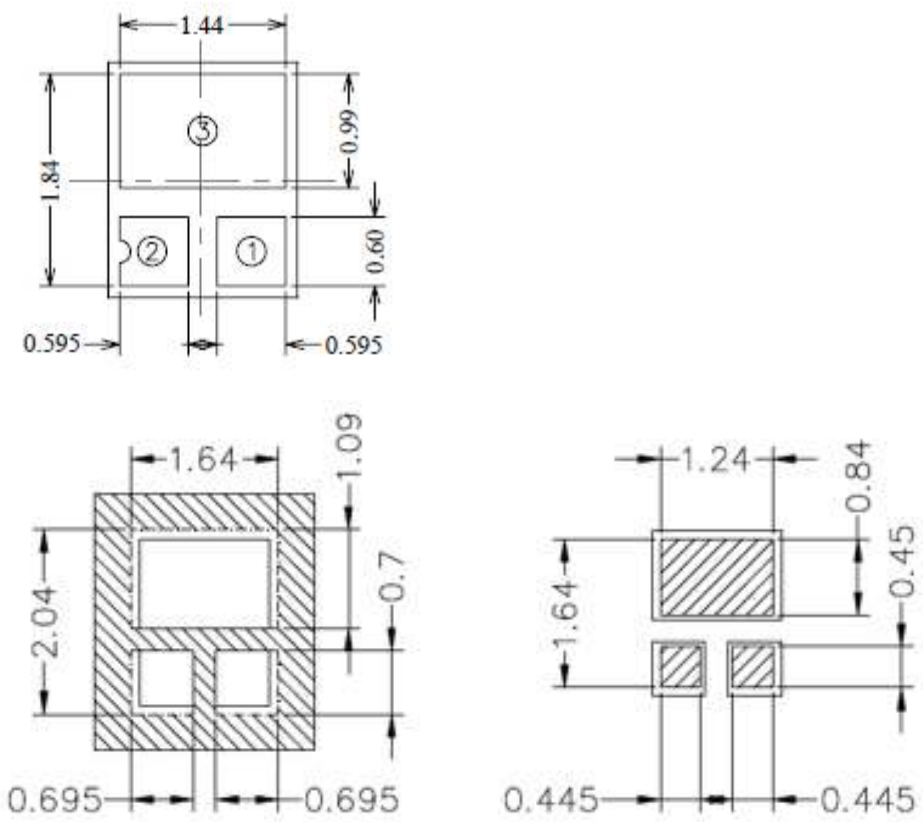
Polarity

①	Anode
②	Cathode
③	Thermal pad

Notes:

- 1. Dimensions are in millimeters.
- 2. Tolerances unless mentioned are $\pm 0.1\text{mm}$.

Recommended Soldering Pad



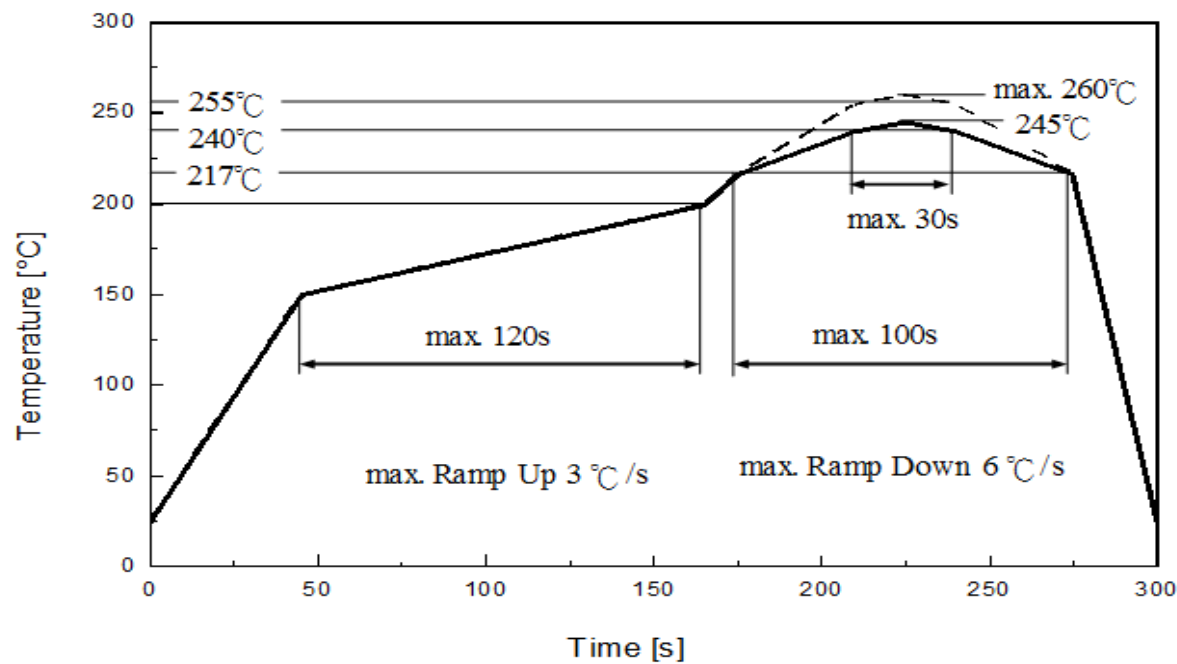
 solder resist

 solder stencil

(Unit: mm)

9. Reflow Soldering Profile

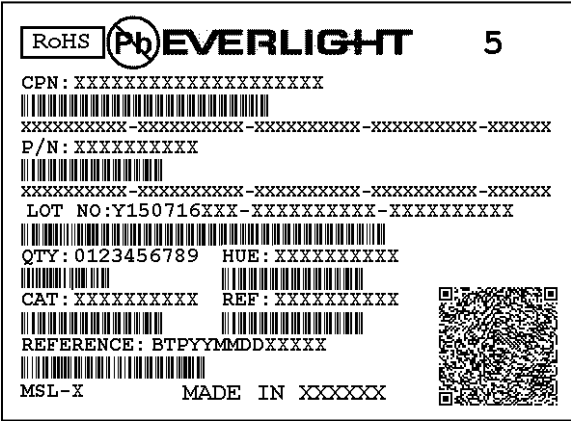
Soldering Condition (Reference: IPC/JEDEC J-STD-020D)



Profile Feature	Pb-Free Assembly	Unit Einheit
Ramp-up rate to preheat 25 °C to 150 °C	3	°C /sec
Time of soaking zone 150 °C to 200 °C	120	sec
Ramp-up rate to peak	3	°C /sec
Liquidus temperature	217	°C
Time above liquidus temperature	100	sec
Peak temperature (max.)	260	°C
Time within 5°C of the specified peak temperature	30	sec
Ramp-down Rate (max.)	6	°C /sec

10. Packaging Information

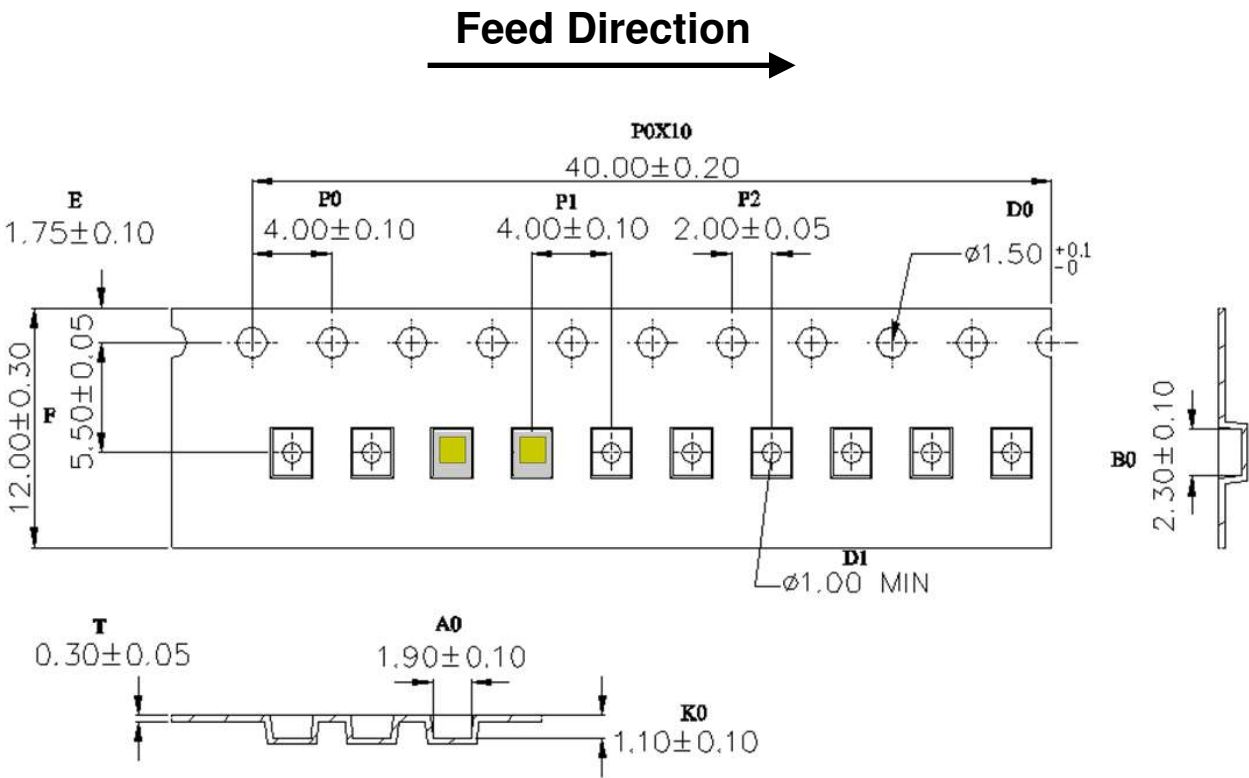
• Product Labeling



- CPN : Customer's Product Number
- P/N : Everlight Part Number
- LOT NO : Lot Number
- QTY : Packing Quantity
- HUE : Color Bin
- CAT : Luminous Flux (Brightness) Bin
- REF : Forward Voltage Bin

• Carrier Tape Dimensions as the following

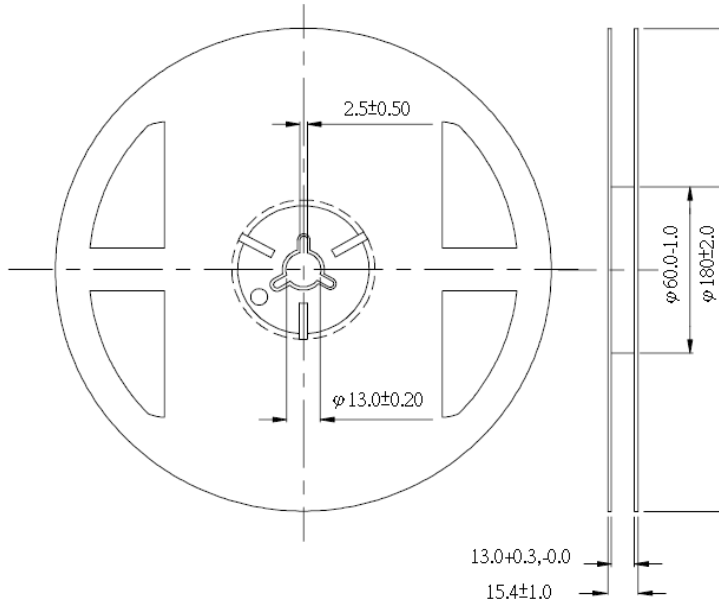
Reel: 1000pcs, MOQ_≥ 100pcs (has to be a multiple of 100pcs)



Notes:

1. Dimensions are in millimeters.

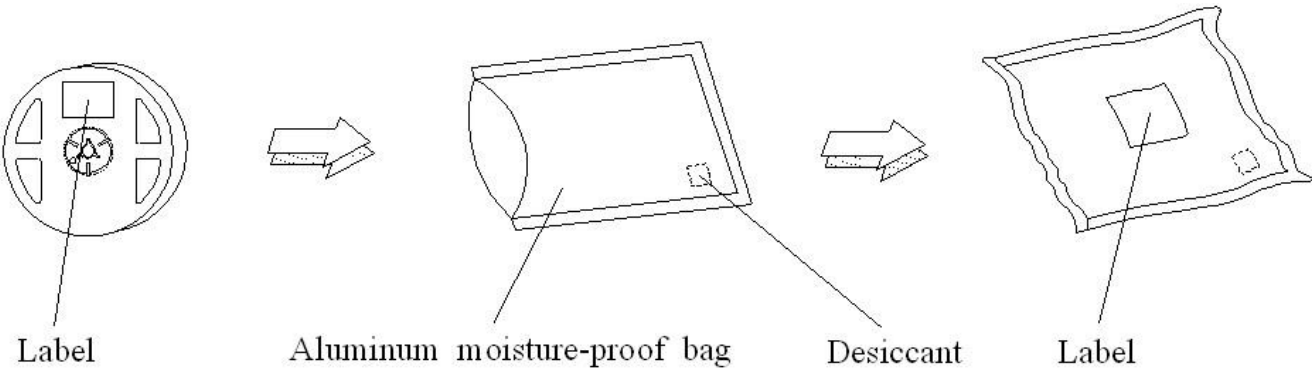
● Reel Dimensions



Notes:

1. Dimensions are in millimeters.

● Moisture Resistant Packing Process



11. Precaution for Use

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (burn out will happen).

2. Assemblies

Do not stack assemblies containing LEDs to prevent damage to the optical surface of LEDs. Forces applied to the optical surface may result in the surface being damaged.

3. Soldering Condition

3.1 When soldering, do not put stress on the LEDs during heating.

3.2 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

12. Sulfur Test Criteria

Products		Failure Criteria		
Exterior Lighting products		Luminous Flux +/-20%, forward voltage +/-10%, color coordinates x,y +/-0.01, color wavelength +/- 2 nm Visual defect issue following Everlight's inspection criteria		
Interior lighting products		Luminous Flux +/-30% or +/-50% for some application, forward voltage +/-10%, color coordinates x,y +/-0.02, color wavelength +/- 2 nm Visual defect issue following Everlight's inspection criteria		
Grade of H2S and FMG test		Please refer to the table as below. As for discolor, please refer to the Frame blackening after Grade of H2S and FMG test defect under Everlight's inspection criteria		
	Grade A0	Grade A1	Grade B0	Grade B1
C12 H2S Class A C13 FMG	No corrosion	Corrosion without the impact on reliability and life time, following AEC-Q102 rev. A		
C12 H2S Class B C13 FMG			No corrosion	Corrosion without the impact on reliability and life time, following AEC-Q102 rev. A
Class for H2S Test & FMG		Description		
		H2S	FMG	
Class A		15 ppm with duration 336 h at 40 °C and 90% RH.	Duration 500 h at 25 °C and 75% RH. H2S concentration: 10ppb SO2 concentration: 200ppb NO2 concentration: 200ppb Cl2 concentration: 10ppb	
Class B		10 ppm with duration 500 h at 25 °C and 75% RH.		
Class for H2S Test & FMG		Description		
0		No corrosion found		
1		Corrosion without the impact on reliability and life time, following AEC-Q102 rev. A		

Revision History

Current version: July, 18, 2025

Issue No: DHE-0003753

Version: 3

Created by : Chris Chuang

Rev.	Subjects (major change in previous version)	Modified date
1	Standard data sheet	2020/08/07
2	Update Dimension & robustness information	2023/08/30
3	Update Color 、 Update Color Bin	2025/7/18